

SOT1011-1

plastic thermal enhanced low profile quad flat package; no leads; 48 terminals; body 7 x 7 x 1.28 mm

8 February 2016

Package information

1. Package summary

Terminal position code	Q (quad)
Package type descriptive code	HLQFN48R
Package type industry code	HLQFN48R
Package style descriptive code	HLQFN (thermal enhanced low profile quad flatpack; no leads)
Package style suffix code	R (resin based)
Package body material type	P (plastic)
Mounting method type	S (surface mount)
Issue date	14-11-2007

Table 1. Package summary

Symbol	Parameter	Min	Typ	Nom	Max	Unit
D	package length	6.9	-	7	7.1	mm
E	package width	6.9	-	7	7.1	mm
A	seated height	[tbd]	-	1.28	1.3	mm
A ₂	package height	[tbd]	-	1.28	1.3	mm
e	nominal pitch	-	-	0.5	-	mm
n ₂	actual quantity of termination	-	-	48	-	

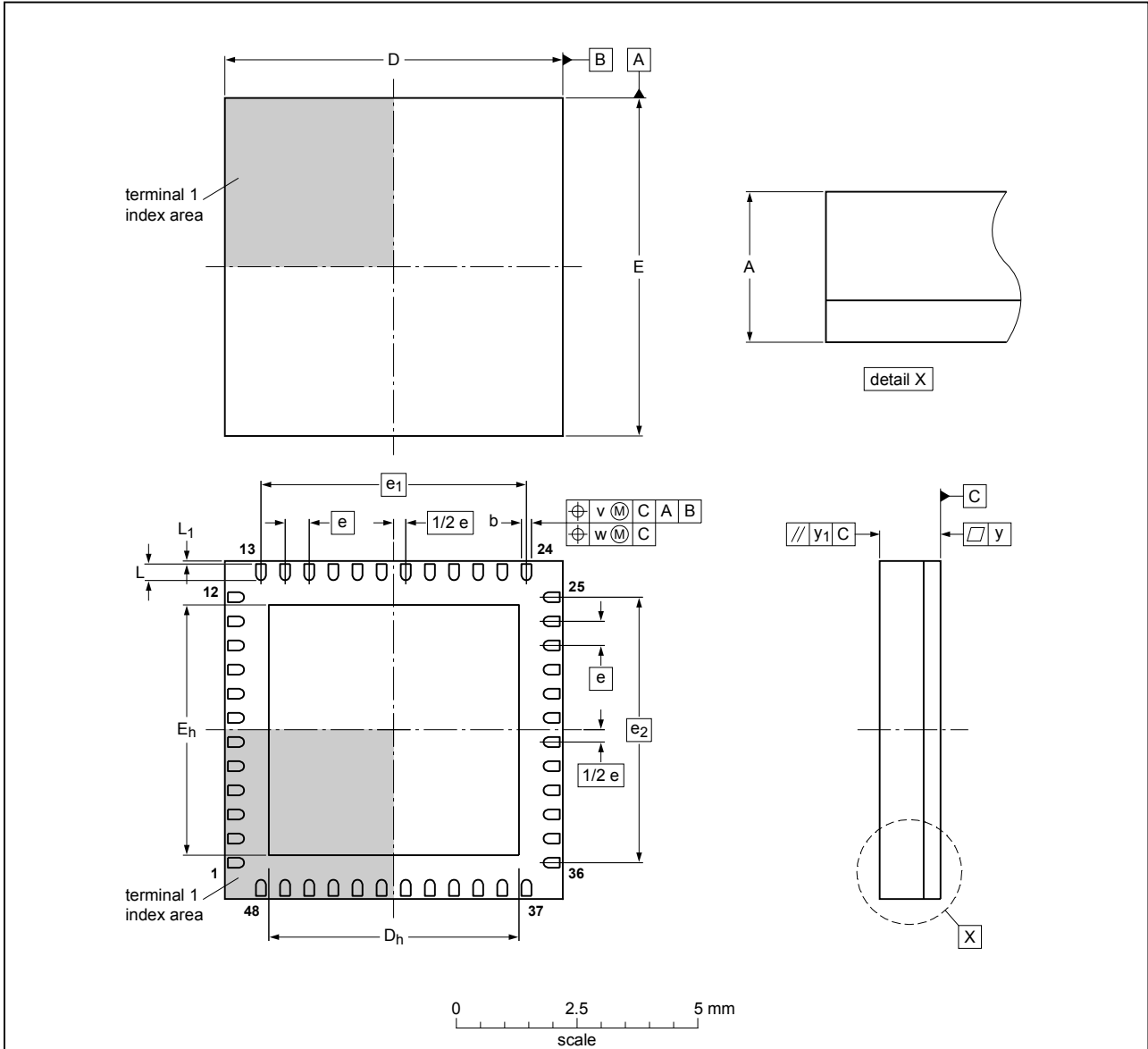


plastic thermal enhanced low profile quad flat package; no leads; 48 terminals; body 7 x 7 x 1.28 mm

2. Package outline

HLQFN48R: plastic thermal enhanced low profile quad flat package; no leads; 48 terminals; resin based; body 7 x 7 x 1.28 mm

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DIMENSIONS (mm are the original dimensions)

UNIT	A _{max}	b	D	D _h	E	E _h	e	e ₁	e ₂	L	L ₁	v	w	y	y ₁
mm	1.3	0.25 0.15	7.1 6.9	5.1 4.9	7.1 6.9	5.1 4.9	0.5	5.5	5.5	0.45 0.35	0.05	0.15	0.05	0.08	0.1

OUTLINE VERSION	REFERENCES				EUROPEAN PROJECTION	ISSUE DATE
	IEC	JEDEC	JEITA			
SOT1011-1	---	---	---			07-05-25 07-11-14

Fig. 1. Package outline HLQFN48R (SOT1011-1)

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package; no leads; 48 terminals; body 7 x 7 x
1.28 mm

3. Legal information

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